PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Jung Hoo SEO	05/15/2009
Suk Jin KANG	05/15/2009

RECEIVING PARTY DATA

Name:	Seoul Semiconductor Co., Ltd.	
Street Address:	148-29 Gasan-dong, Geumcheon-gu	
City:	Seoul	
State/Country:	REPUBLIC OF KOREA	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12059296

CORRESPONDENCE DATA

Fax Number: (703)288-5139

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 703-288-5105

Email: patent@park-law.com

Correspondent Name: H.C. Park & Associates, PLC

Address Line 1: 8500 Leesburg Pike, Suite 7500

Address Line 4: Vienna, VIRGINIA 22182

ATTORNEY DOCKET NUMBER: P2304US00

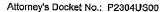
NAME OF SUBMITTER: Hae-Chan Park

Total Attachments: 2

source=P2304US00 Assignment#page1.tif source=P2304US00 Assignment#page2.tif

OP \$40.00 120592

PATENT REEL: 022747 FRAME: 0767





ASSIGNMENT

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in

an application for United States Letters Patent entitled LED PACKAGE ("Application");

upon which United States Letters Patent, Patent Number _______, has issued ("Patent");

Whereas, Assignor desires to convey all rights, titles, and interests in and to the same to:

Seoul Semiconductor Co. Ltd. 1B-36, 727-5, Wonsi-dong, Danwon-gu Gyeonggi-do Ansan-si South Korea

Seoul Semiconductor Co. Ltd. herein further referred to as ("Assignee").

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the US or any and all foreign countries and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.



Date:

RECORDED: 05/28/2009

IN WITNESS WHEREOF, Assignor has hereunto set hand and seal. First Inventor's Name: Jung Hoo SEO Address: 148-29 Gasan-dong, Geumcheon-gu 153-801 Seoul South Korea First Inventor's Signature: Date: Second Inventor's Name: Suk Jin KANG Address: 1-35 Block, 727-5, Wonsi-dong, Danwon-gu Gyeonggi-do 425-851 Ansan-si South Korea 75 Kg2V Second Inventor's Signature:

May

15, 2009